



(1,27 mm) .050"

CLP-107-02-F-D-P

CLP-115-02-L-D

CLP-130-02-L-D

CLP-116-02-F-DH

CLP SERIES

LOW PROFILE DUAL WIPE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLP

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

Phosphor Bronze

Plating:

Sn or Au over

50µ" (1,27 µm) Ni

Current Rating (CLP/FTSH):

3.3 A per pin

(1 pin powered per row)

Voltage Rating:

240 VAC/340 VDC

Operating Temp Range:

-55°C to +125°C

Contact Resistance:

10 mΩ

Insertion Depth:

Top Entry = (1,40 mm) .055"

minimum, Bottom Entry =

(2,41 mm) .095" minimum

plus board thickness

DH Entry = (2,31 mm) .091"

to (2,67 mm) .105"

Insertion Force:

(Single contact only)

3.8 oz (1,05 N) average

Normal Force:

60 grams (0,59 N) average

Withdrawal Force:

(Single contact only)

2 oz (0,56 N) average

Max Cycles:

100 with 10µ" (0,25 µm) Au

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,10 mm) .004" max (02-35)

(0,15 mm) .006" max (36-50)

Mates with:
FTSH, FTS, FW

APPLICATIONS

CLP FTSH

HORIZONTAL

PASS-THRU

High reliability
Tiger Claw™
contacts

(1,27 mm x 1,27 mm)
.050" x .050"
micro pitch

Low Profile
(2,21 mm)
.087"

Surface
Mount

Suitable for pass-through
applications

